

Supplementary Information

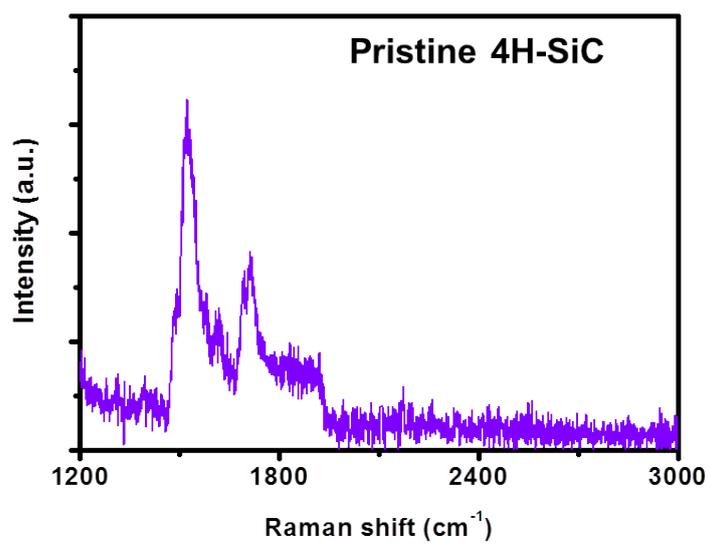
Scalable Graphene Synthesized by Plasma-Assisted Selective Reaction Process on Silicon Carbide for Device Application

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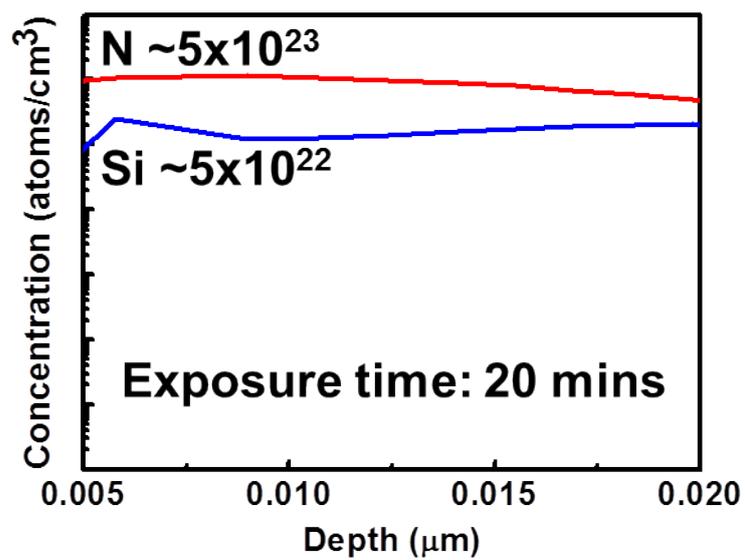
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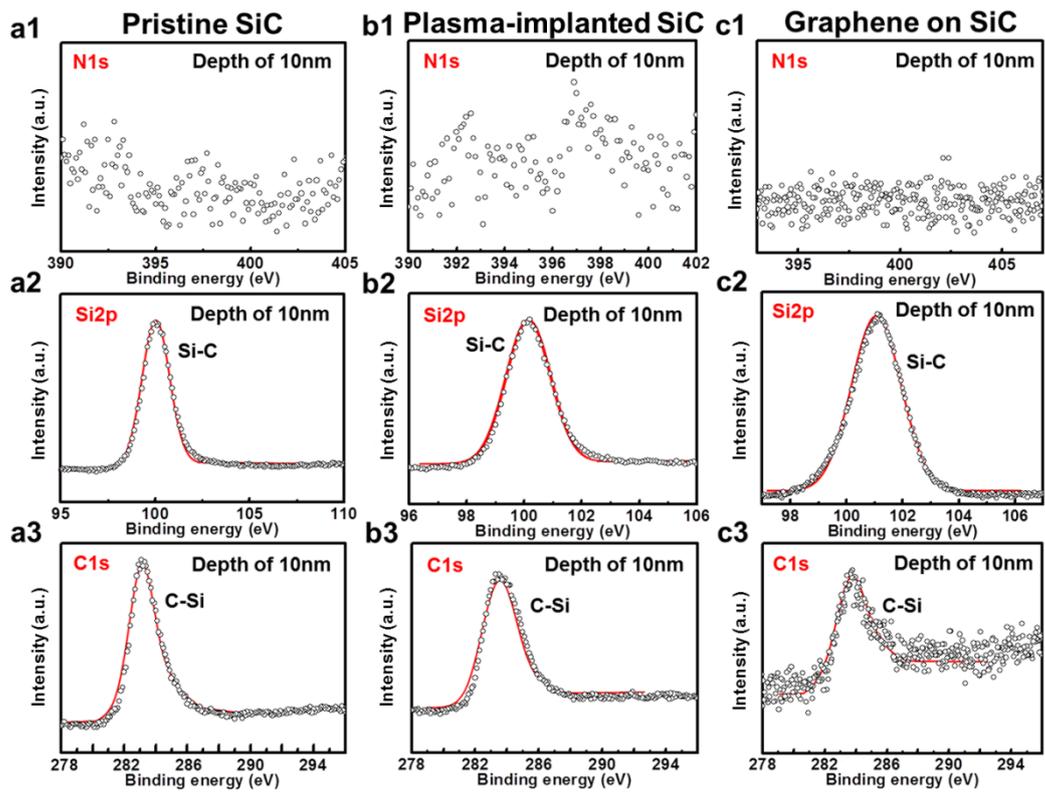
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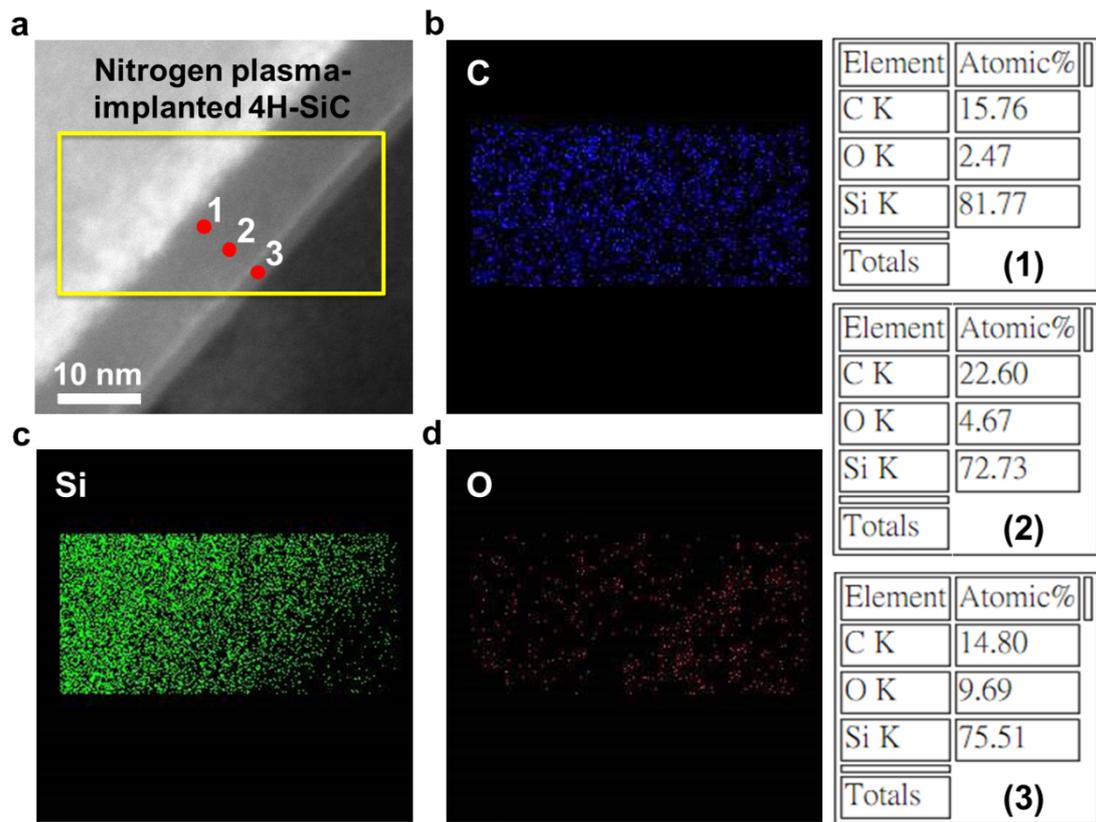
Supplementary Figure 1 Raman spectrum. Raman spectrum of pristine 4H-SiC.



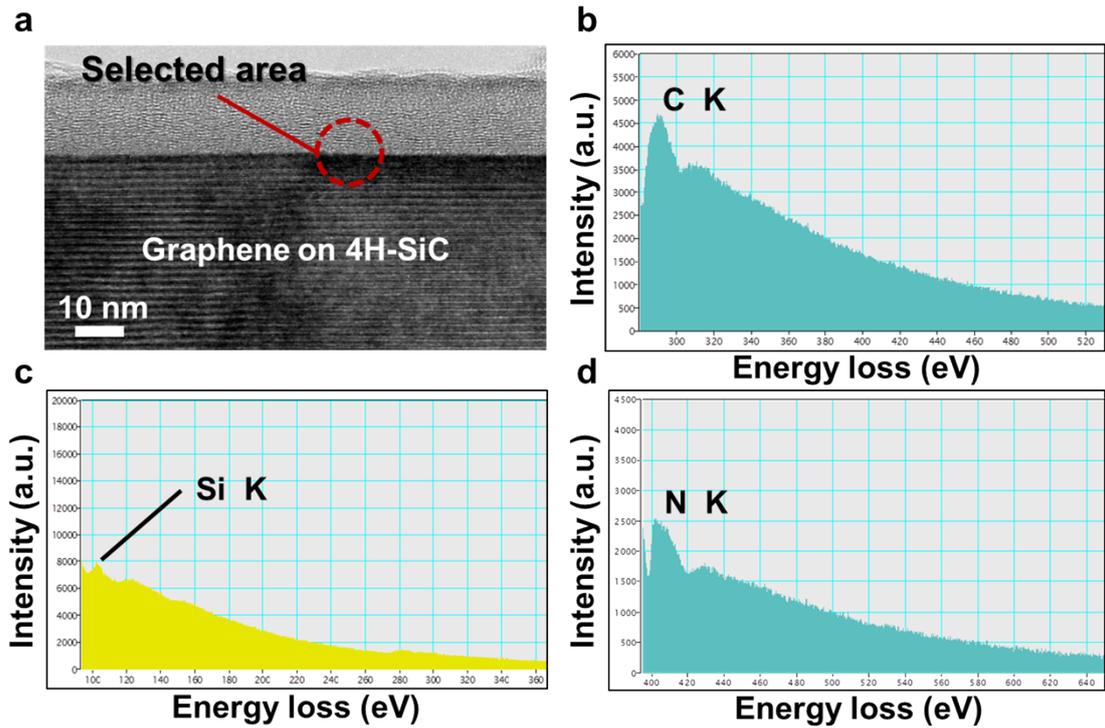
Supplementary Figure 2 SIMS depth concentration profile. The depth concentration of nitrogen in Si substrate.



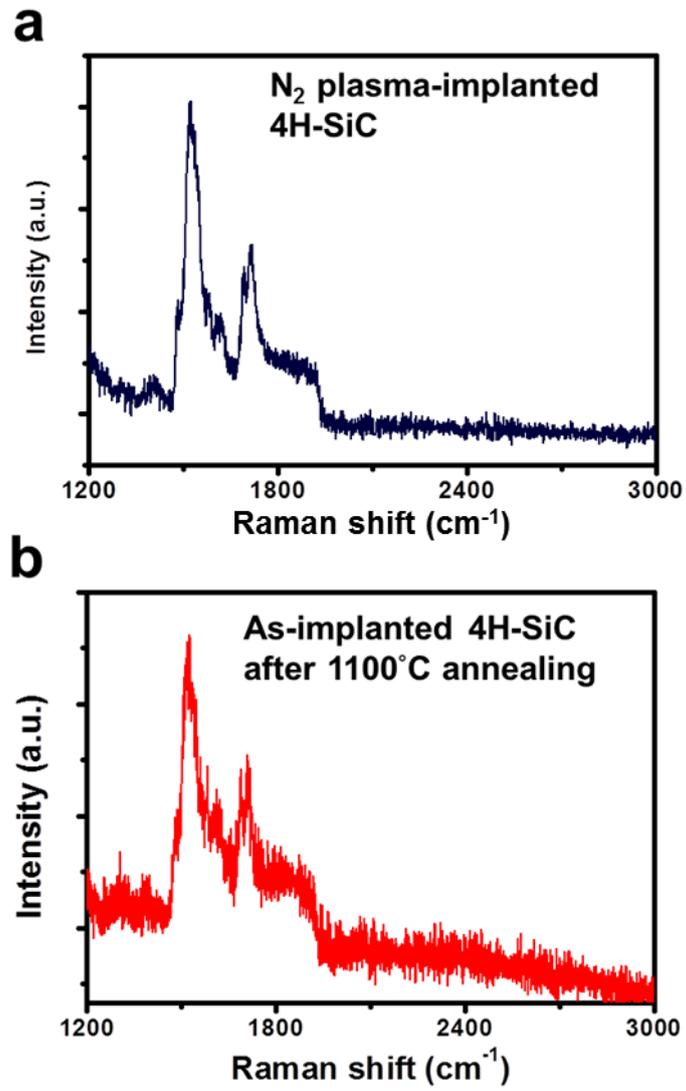
Supplementary Figure 3 XPS spectra of 10 nm-depth below the surface. a, N1s (a1), Si2p (a2), and C1s (a3) spectra of pristine SiC. **b,** N1s (b1), Si2p (b2), and C1s (b3) spectra of plasma-implanted SiC. **c,** N1s (c1), Si2p (c2), and C1s (c3) spectra of graphene on SiC.



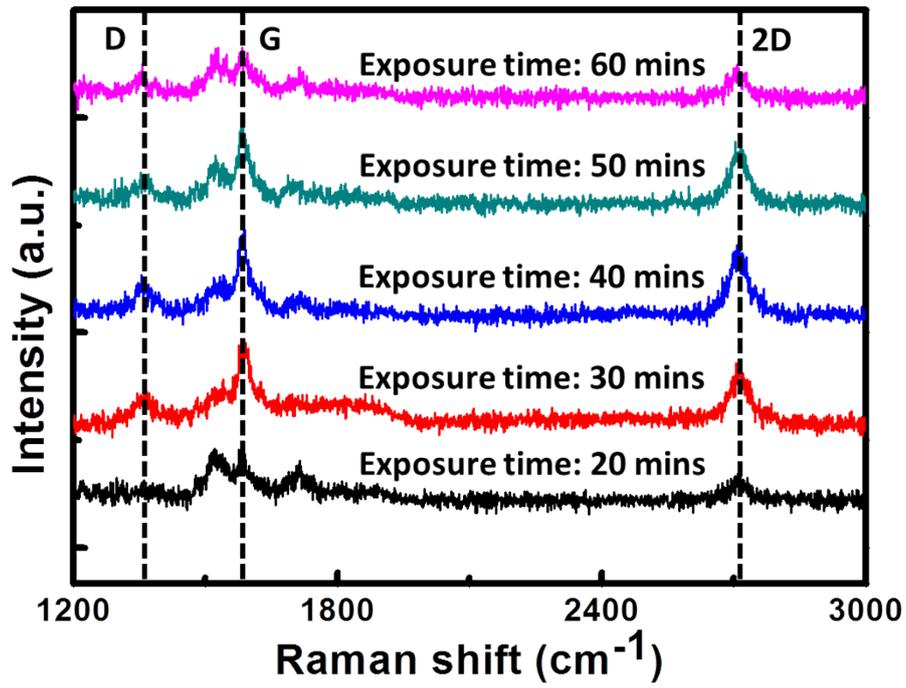
Supplementary Figure 4 TEM observation and EDS mapping. **a**, Cross-sectional TEM image of plasma-implanted SiC and the red dots indicate the depth of EDS line-scan. **b**, C EDS mapping of the area within yellow frame in **a**. **c**, Si EDS mapping of the area within yellow frame in **a**. **d**, O EDS mapping of the area within yellow frame in **a**.



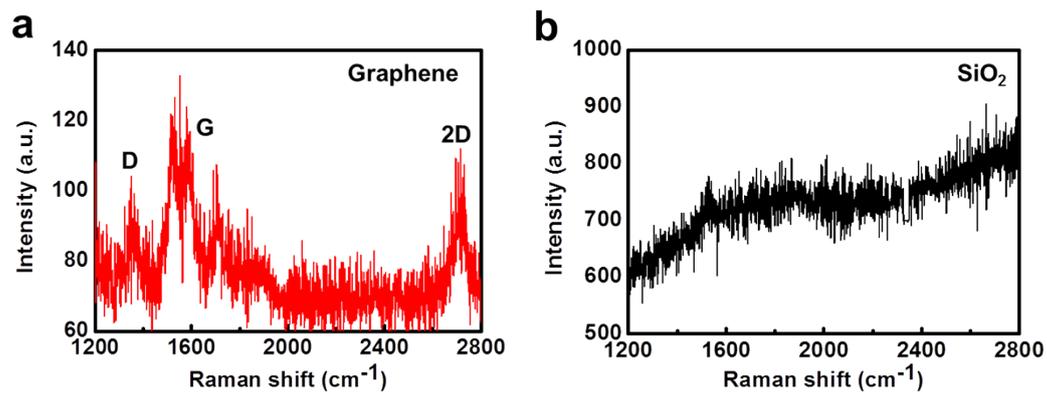
Supplementary Figure 5 TEM observation and EELS spectra. a, Cross-sectional TEM image of graphene on SiC and the red circle indicates the selected area. **b,** C K-edge EELS spectrum of the region within red circle in **a**. **c,** Si K-edge EELS spectrum of the region within red circle in **a**. **d,** N K-edge EELS spectrum of the region within red circle in **a**.



Supplementary Figure 6 Raman spectra. a, Raman spectrum of plasma-implanted 4H-SiC. **b,** Raman spectrum of plasma-implanted 4H-SiC after 1100°C annealing.

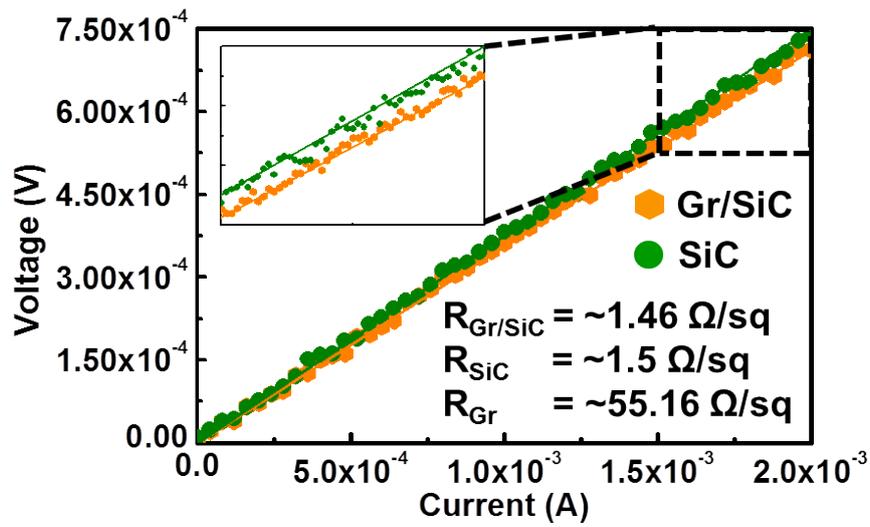


Supplementary Figure 7 Raman spectra. Raman spectra of graphene obtained by PSR process with different plasma exposure times.

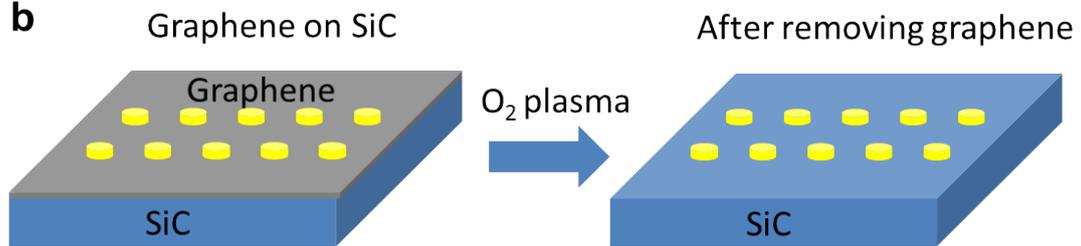


Supplementary Figure 8 Raman spectra. a, Raman spectrum of patterned graphene on SiC. **b,** Raman spectrum of patterned SiO_2 on SiC.

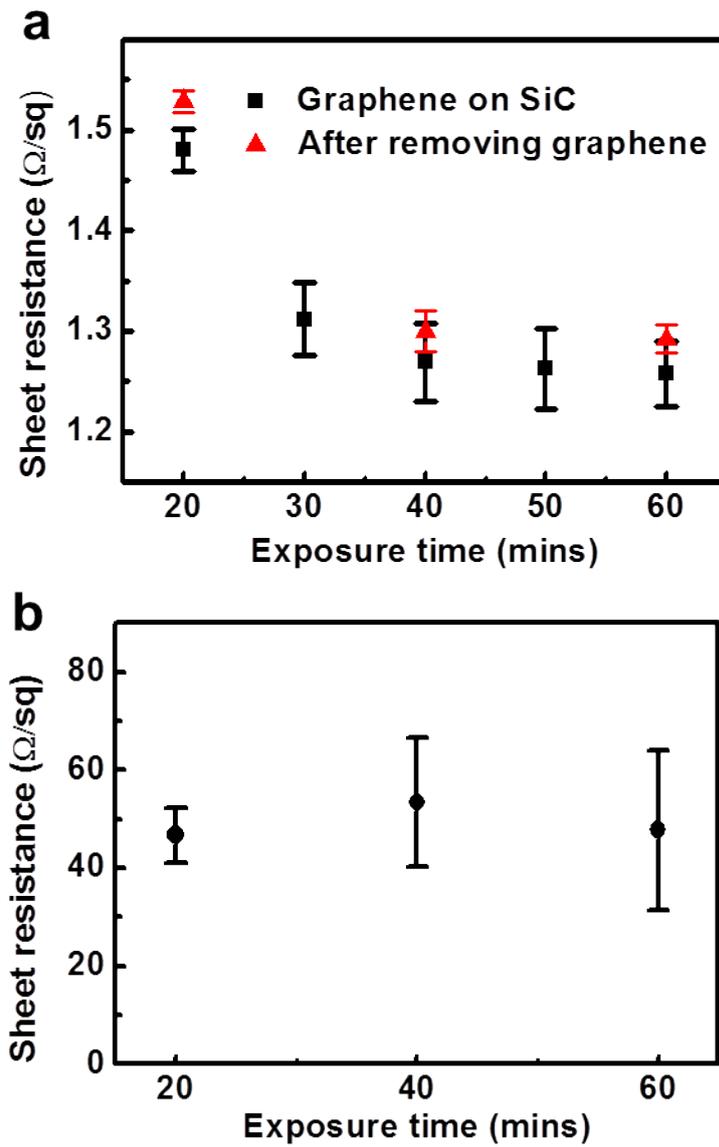
a



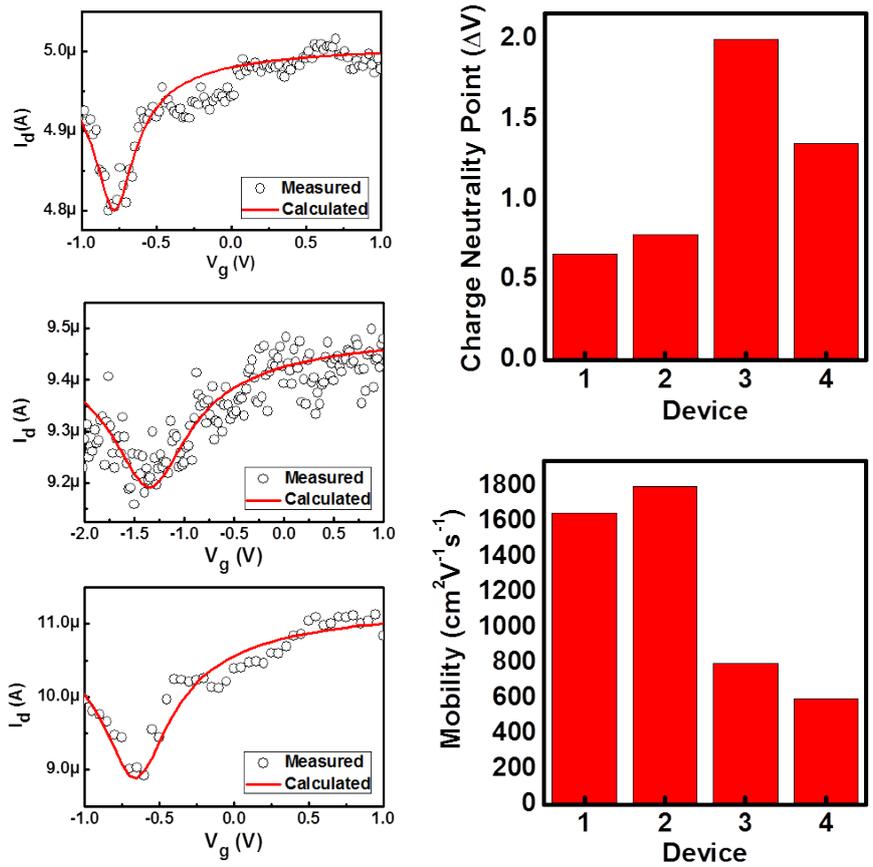
b



Supplementary Figure 9 Four-probe measurement. a, I-V behavior of graphene on SiC and pure SiC after removal of graphene. **b**, schematic of the process for removing graphene.



Supplementary Figure 10 Sheet resistance. **a**, sheet resistances of SiC after the PSR process with different plasma exposure times before and after removal of graphene. **b**, Estimated sheet resistances of graphene films extracted from **a**.



Supplementary Figure 11 Device characteristics. I_{ds} - V_g behavior of graphene FETs on SiC and the statistical results of mobility and charge neutrality point.